

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}$	I_D $T_A = +25^\circ\text{C}$
20V	3.0Ω @ $V_{GS} = 4.5\text{V}$	240mA
	6.0Ω @ $V_{GS} = 1.8\text{V}$	180mA

Description

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- DC-DC Converters
- Power Management Functions

Features

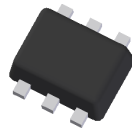
- Dual N-Channel MOSFET
- Low On-Resistance:
 - 3.0Ω @ 4.5V
 - 4.0Ω @ 2.5V
 - 6.0Ω @ 1.8V
 - 10Ω @ 1.5V
- Very Low Gate Threshold Voltage, 1.05V Max
- Low Input Capacitance
- Fast Switching Speed
- Ultra-Small Surface Mount Package
- ESD Protected Gate (HBM 300V)
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

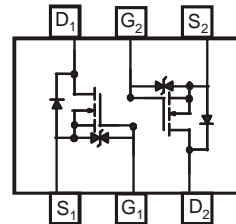
- Case: SOT963
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.0027 grams (Approximate)



SOT963



Top View



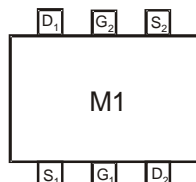
Top View
Schematic and Transistor Diagram

Ordering Information (Note 4)

Part Number	Case	Packaging
DMN26D0UDJ-7	SOT963	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information (Note 5)



M1 = Product Type Marking Code

Note: 5. Package is non-polarized. Parts may be on reel in orientation illustrated, 180° rotated, or mixed (both ways).

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain Source Voltage			V _{DSS}	20	V
Gate-Source Voltage			V _{GSS}	±10	V
Continuous Drain Current (Note 6) V _{GS} = 4.5V	Steady State	T _A = +25°C	I _D	240	mA
		T _A = +70°C		190	
Continuous Drain Current (Note 6) V _{GS} = 1.8V	Steady State	T _A = +25°C	I _D	180	mA
		T _A = +70°C		140	
Pulsed Drain Current - T _P = 10μs			I _{DM}	805	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 6)	P _D	300	mW
Thermal Resistance, Junction to Ambient (Note 6)	R _{θJA}	409	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	20	—	—	V	V _{GS} = 0V, I _D = 100μA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	500 1.7	nA μA	@ T _J = +25°C V _{DS} = 20V, V _{GS} = 0V @ T _J = +85°C (Note 8) V _{DS} = 2.6V, V _{GS} = 0V
Gate-Body Leakage	I _{GSS}	—	—	±1 ±100	μA nA	V _{GS} = ±10V, V _{DS} = 0V V _{GS} = ±5V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(th)}	0.45	0.8	1.05	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS (ON)}	—	1.8	3.0	Ω	V _{GS} = 4.5V, I _D = 100mA
		—	2.5	4.0		V _{GS} = 2.5V, I _D = 50mA
		—	3.4	6.0		V _{GS} = 1.8V, I _D = 20mA
		—	4.7	10.0		V _{GS} = 1.5V, I _D = 10mA
		—	9.5	—		V _{GS} = 1.2V, I _D = 1mA
Forward Transconductance	Y _{fs}	180	240	—	mS	V _{DS} = 10V, I _D = 0.1A
Source-Drain Diode Forward Voltage	V _{SD}	0.5	0.8	1.0	V	V _{GS} = 0V, I _S = 10mA
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	—	14.1	—	pF	V _{DS} = 15V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{oss}	—	2.9	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	1.6	—	pF	
SWITCHING CHARACTERISTICS, V _{GS} = 4.5V (Note 8)						
Turn-On Delay Time	t _{d(on)}	—	3.8	—	ns	V _{GS} = 4.5V, V _{DD} = 10V I _D = 200mA, R _G = 2.0Ω
Rise Time	t _r	—	7.9	—		
Turn-Off Delay Time	t _{d(off)}	—	13.4	—		
Fall Time	t _f	—	15.2	—		

- Notes:
- Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch with minimum recommended pad layout; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com>.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design, not subject to production testing.

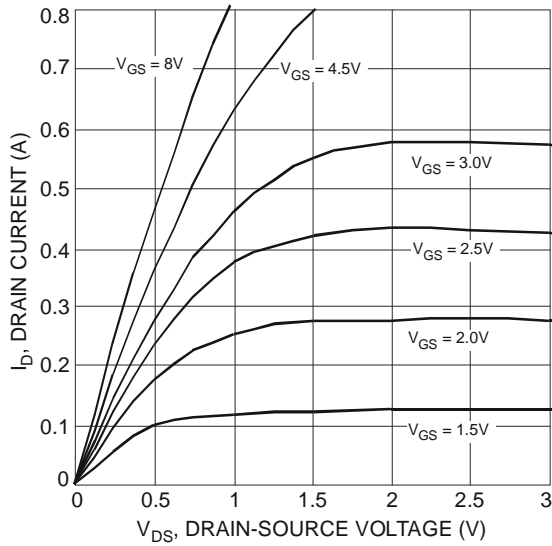


Fig. 1 Typical Output Characteristic

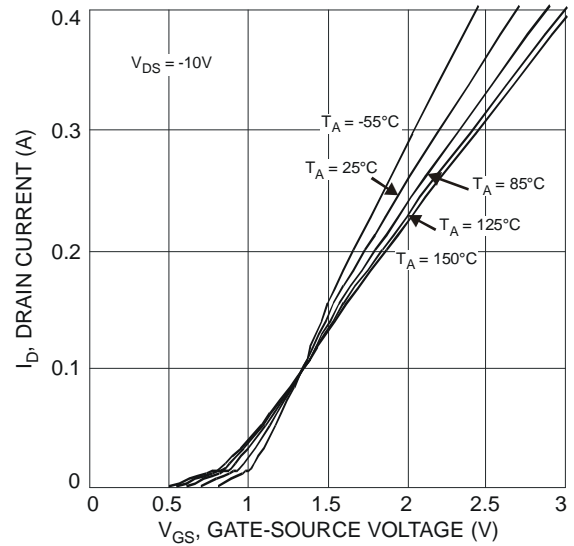


Fig. 2 Typical Transfer Characteristic

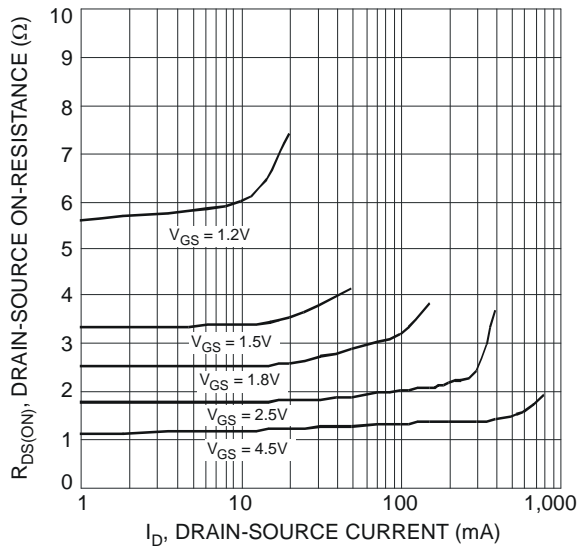


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

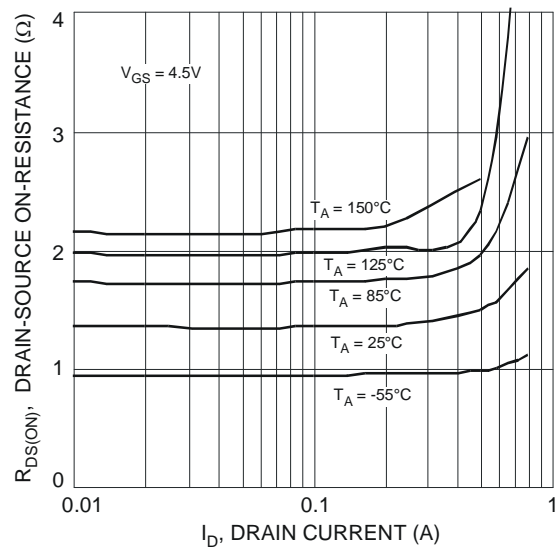


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

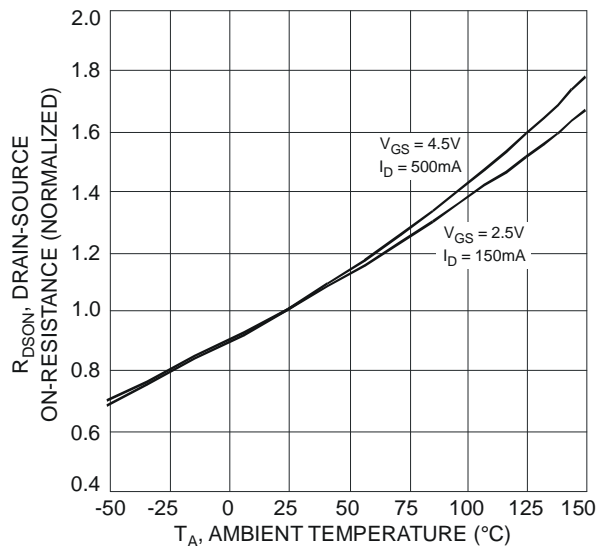


Fig. 5 On-Resistance Variation with Temperature

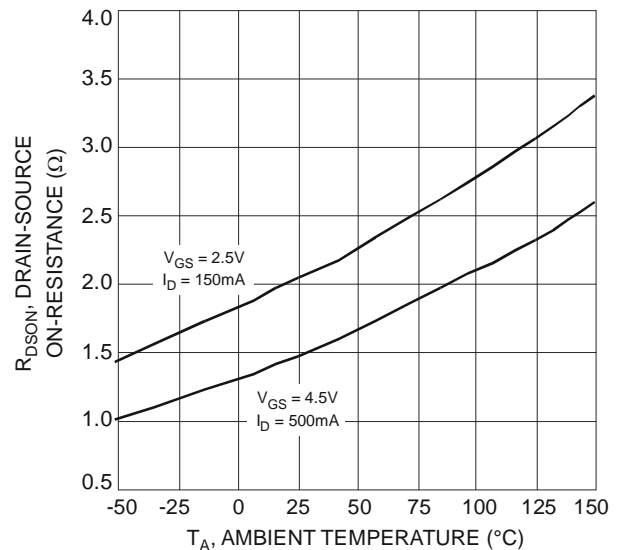


Fig. 6 On-Resistance Variation with Temperature

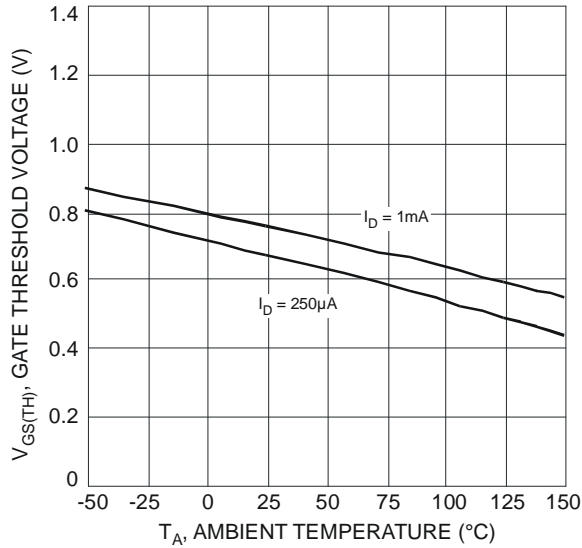


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

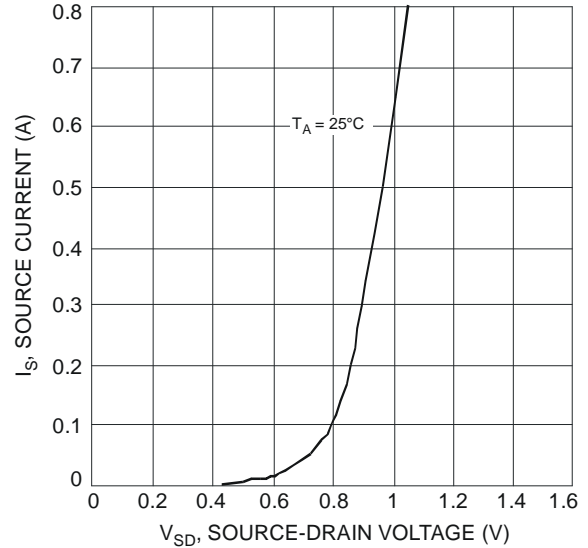


Fig. 8 Diode Forward Voltage vs. Current

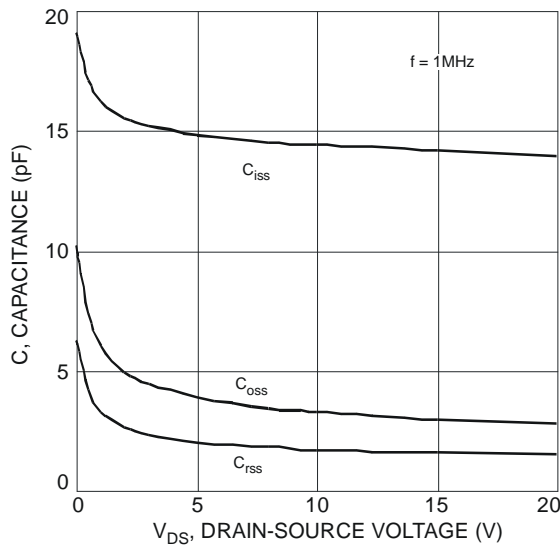


Fig. 9 Typical Total Capacitance

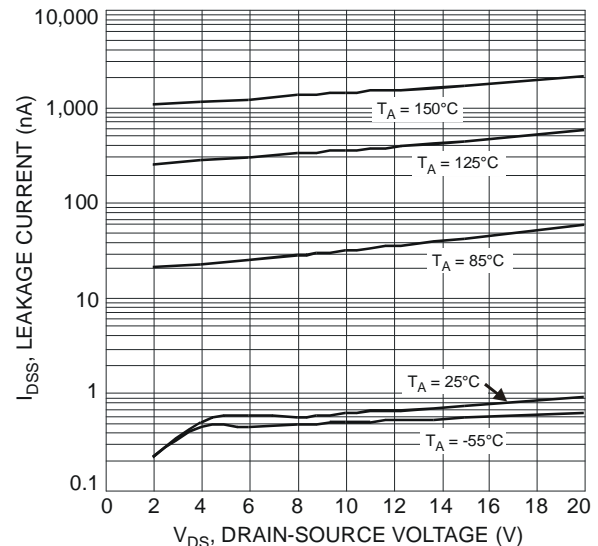
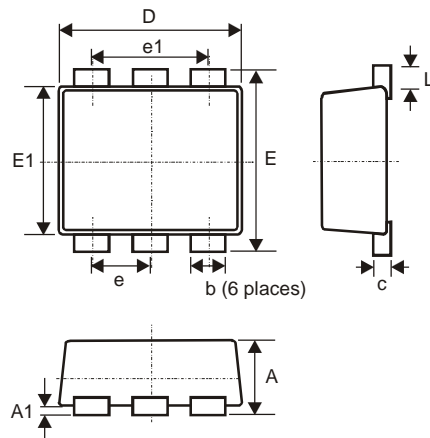


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage

Package Outline Dimensions

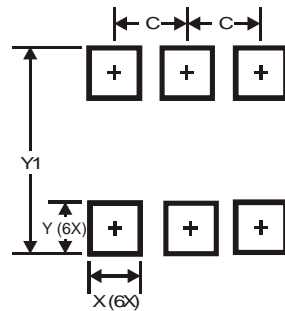
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOT963			
Dim	Min	Max	Typ
A	0.40	0.50	0.45
A1	0	0.05	-
c	0.120	0.180	0.150
D	0.95	1.05	1.00
E	0.95	1.05	1.00
E1	0.75	0.85	0.80
L	0.05	0.15	0.10
b	0.10	0.20	0.15
e	0.35 Typ		
e1	0.70 Typ		
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.350
X	0.200
Y	0.200
Y1	1.100

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